Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
191	26	430/22,30,311,313,322,330.ccls. and ((contribut\$6 near3 degree or proportion or coefficien\$3 or factor\$3 or amount\$3 or percent\$3 or relativ\$3 or grad\$3 or level\$3 or exten\$4) same (resist or photoresist) same (thick\$4 and temperature and pressure and (humidi\$5 or moistur\$6 or wet\$4)))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 10:55
L3	2303	(430/22,30,311,313,322,330.ccls. and (((spin\$4 or rotat\$3 or centrifug\$6) and (expos\$3 or radiat\$3 or irradiat\$3 or light\$3) and develop\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7))) and ((etch\$3 or heat\$3 or bak\$3 or prebak\$3 or postbak\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7)) not 1	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 11:17
14	886	(430/22,30.ccls. not ((((spin\$4 or rotat\$3 or centrifug\$6) and (expos\$3 or radiat\$3 or irradiat\$3 or light\$3) and develop\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7))) and ((etch\$3 or heat\$3 or bak\$3 or prebak\$3 or postbak\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7)))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 11:32
L5	143	427/8-10.ccls. and (etch\$3 or heat\$3 or bak\$3 or prebak\$3 or postbak\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7) not 1 not 3 not 4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 11:42
L6	100	(substrate or wafer) near3 (defect or fault) same (nozzle or pipe or spread\$3 or flow\$3 or dispens\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7) not 1 not 3 not 4 not 5	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 11:57
L8	4	427/8-10.ccls. and (resist or photoresist) same (nozzle or dispens\$3 or spread\$3 or pip\$3 or eject\$3) near3 (accelerat\$3 or decelerat\$3 or position\$3 or location) not 1 not 3 not 4 not 5 not 6	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 12:04

L9	4	427/8-10.ccls. and (resist or photoresist) same (nozzle or	US-PGPUB; USPAT;	OR	ON	2005/04/06 12:08
		dispens\$3 or spread\$3 or pip\$3 or eject\$3) same (accelerat\$3 or decelerat\$3 or position\$3 or location) not 1 not 3 not 4 not 5 not 6 not 8	EPO; JPO; IBM_TDB			
L10	4	(427/8-10 or: 438/5-18).ccls. and ((contribut\$6 near3 degree or proportion or coefficien\$3 or factor\$3 or amount\$3 or percent\$3 or relativ\$3 or grad\$3 or level\$3 or exten\$4) same (resist or photoresist) same (thick\$4 and temperature and pressure and (humidi\$5 or moistur\$6 or wet\$4))) not 1 not 3 not 4 not 5 not 6 not 8 not 9	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 12:11
L11	16	(427/8-10 or 438/5-18).ccls. and (formula\$1 or equation) same (resist or photoresist) same thick\$4 not 1 not 3 not 4 not 5 not 6 not 8 not 9 not 10	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 12:14
L12	53	(430/22,30 or 438/5-18).ccls. and (etch\$3 near3 (line or pattern) same (alarm\$3 or alert\$3 or warn\$3 or buzz\$3 or signal\$4 or notif\$4)) not 1 not 3 not 4 not 5 not 6 not 8 not 9 not 10 not 11	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 12:33
L13	96	semiconduct\$3 and (etch\$3 same (alarm\$3 or alert\$3 or warn\$3 or buzz\$3 or notif\$4) same (operator or human3 or manual\$3 or person\$6 or eye\$3)) not 1 not 3 not 4 not 5 not 6 not 8 not 9 not 10 not 11 not 12	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 12:36
L14	0	(430/22,30 or 438/5-18).ccls. and (etch\$3 near3 (line or pattern) same (alarm\$3 or alert\$3 or warn\$3 or buzz\$3 or signal\$4 or notif\$4)) not 1 not 3 not 4 not 5 not 6 not 8 not 9 not 10 not 11 not 12 not 13	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/04/06 12:38

not 12 not 13